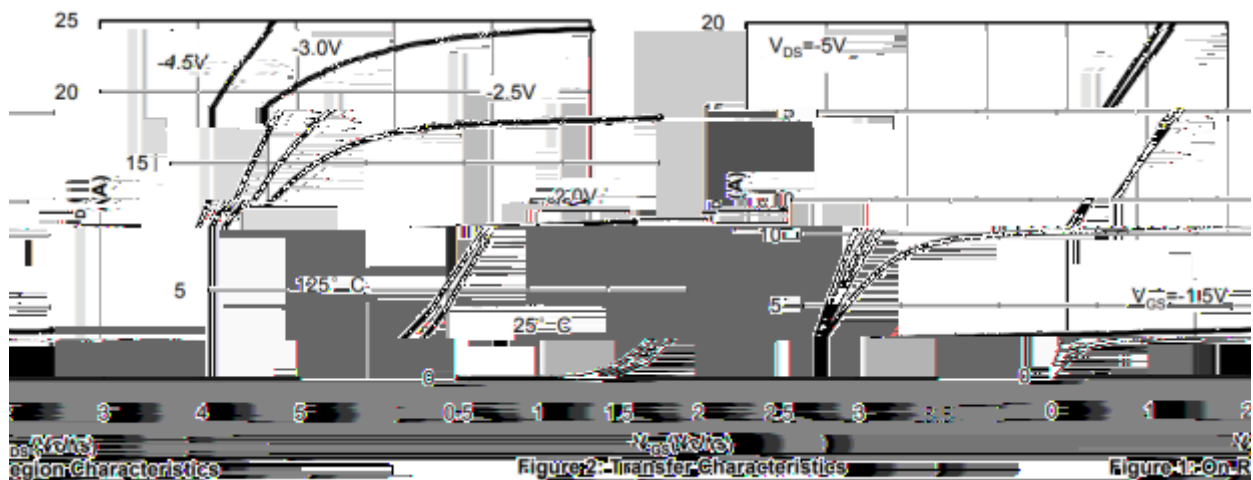
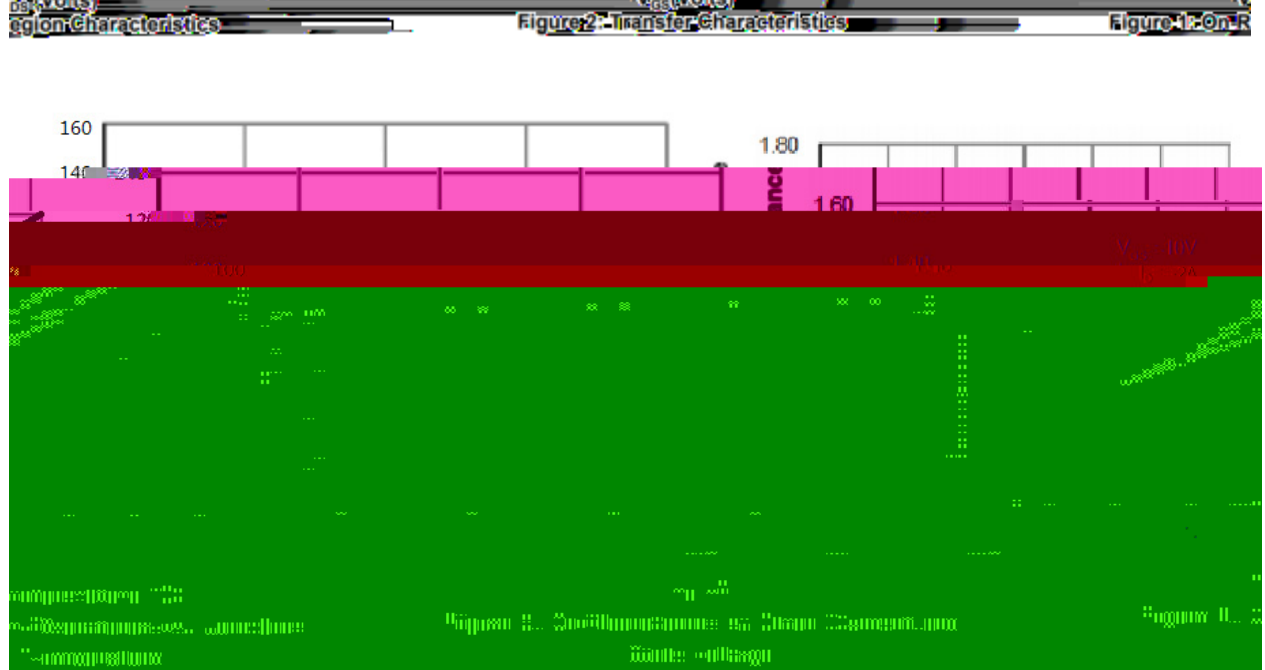
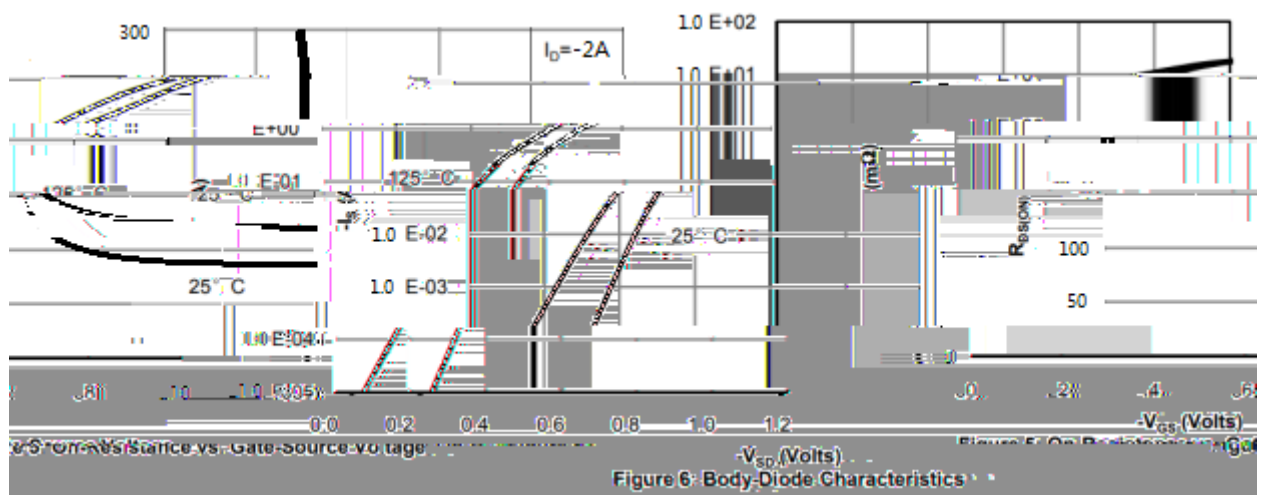
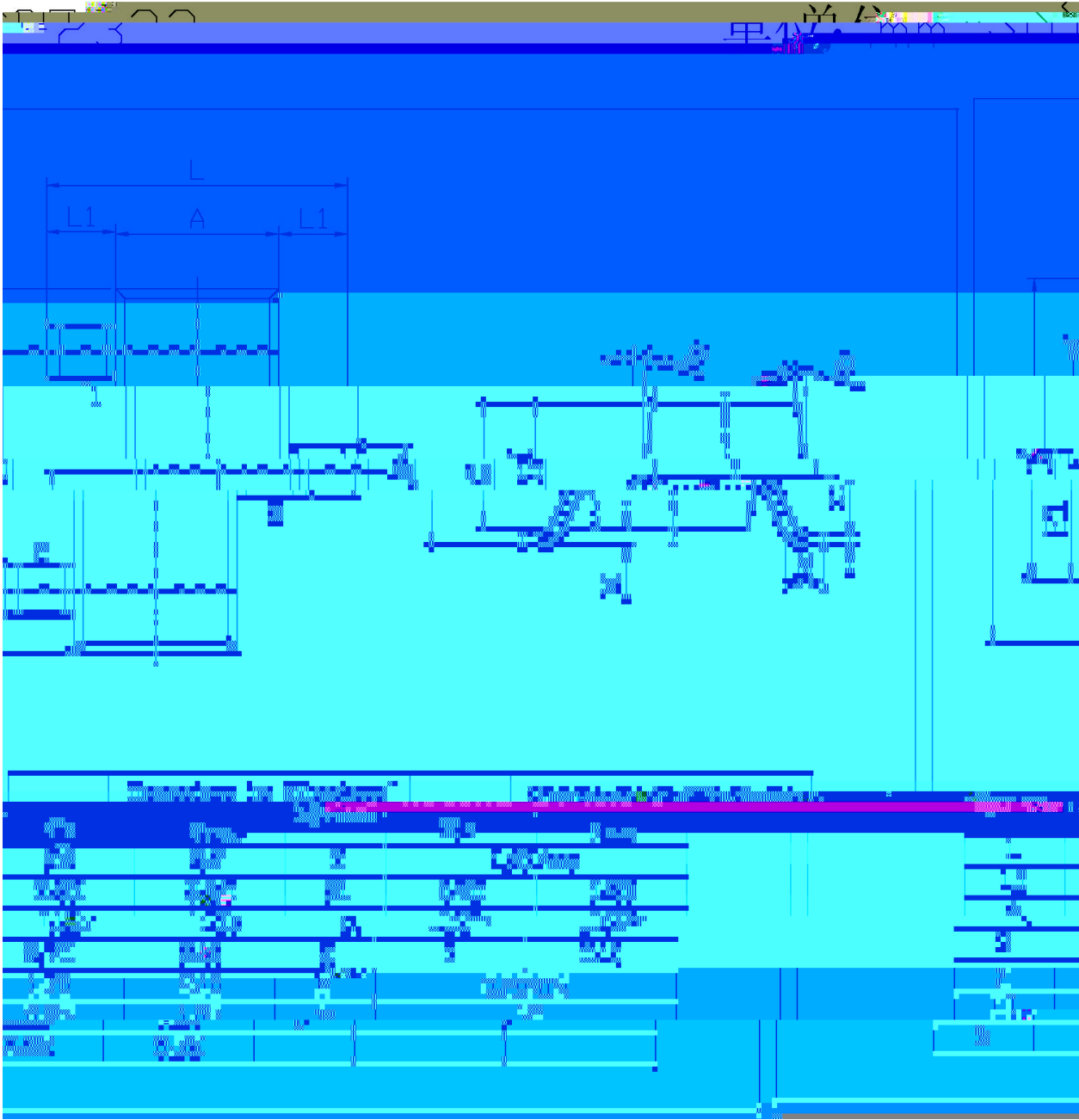


Parameter	Symbol	Rating	Unit
Drain–Source Voltage	V_{DS}	-60	V
Gate–Body Leakage Voltage	V_{GS}	± 20	V
Drain Current - Continuous	I_D	-5	A
Pulsed Drain Current	I_{DM}	-18	A
Power Dissipation (Surface Mounted on FR4 Board, $t \leq 10$ sec.)	P_D	1.5	W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 150	
Maximum Junction-to-Ambient $t \leq 10s$	$R_{\theta JA}$		

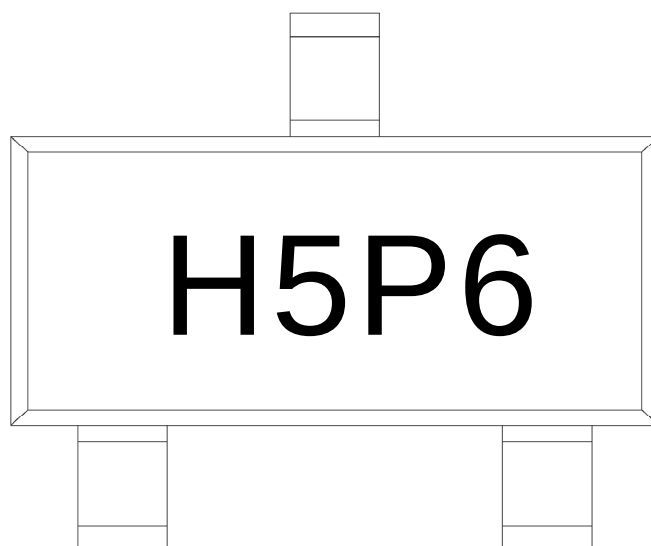
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



H:

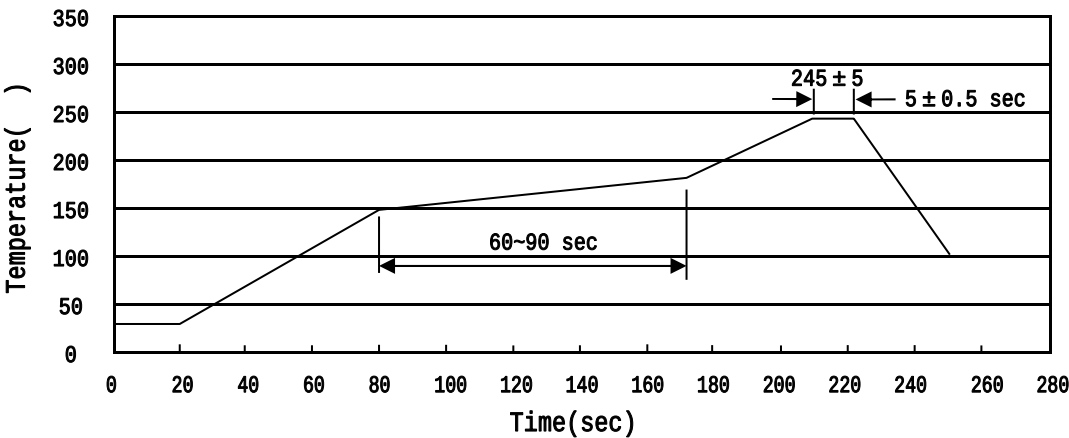
5P6

Note:

H Company Code

5P6: Product Type

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|----|-----------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm ³)

/ Notices